



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

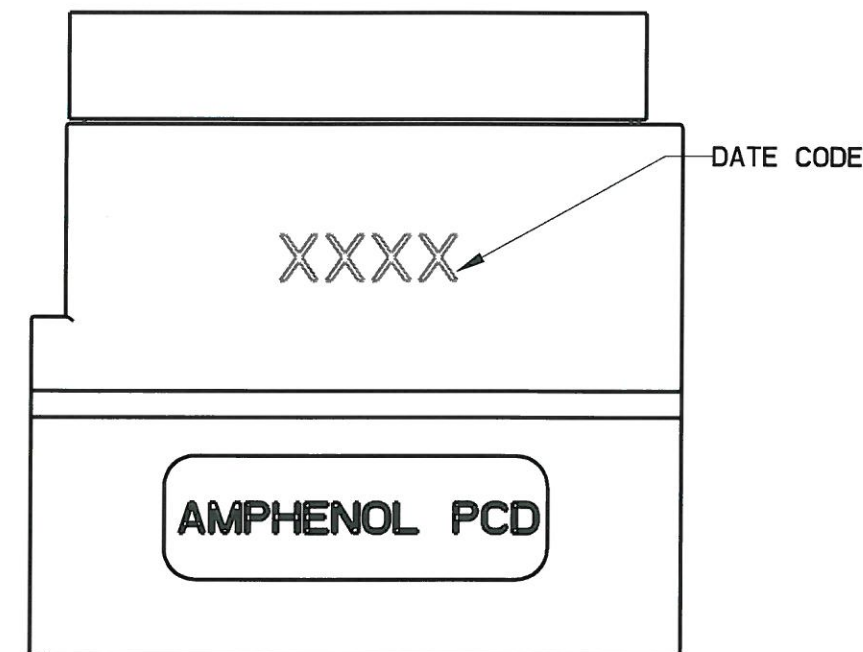
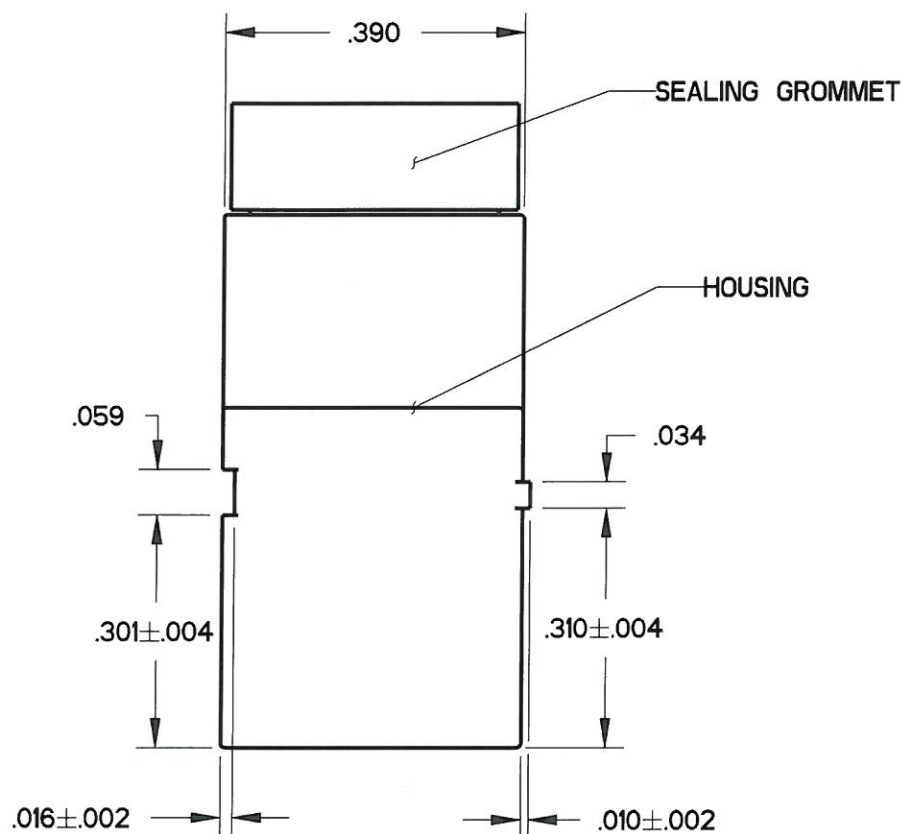
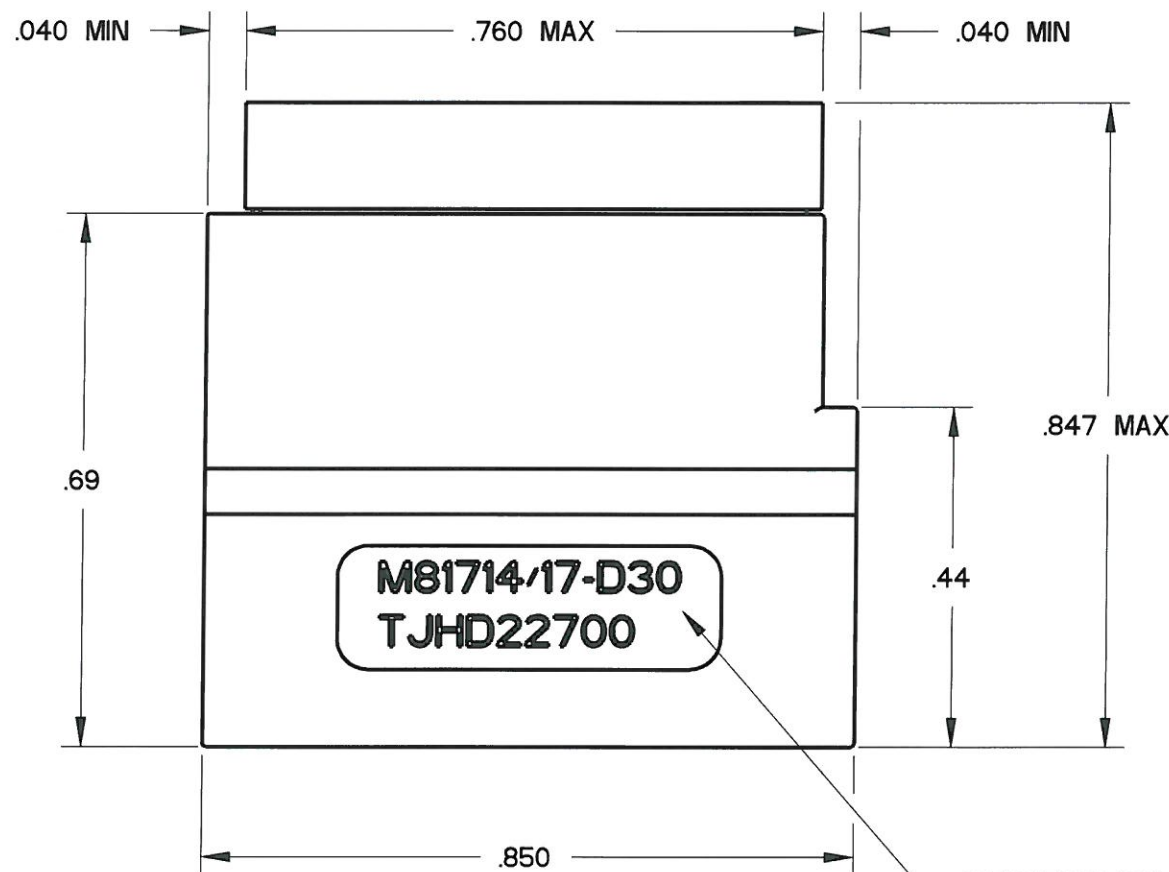
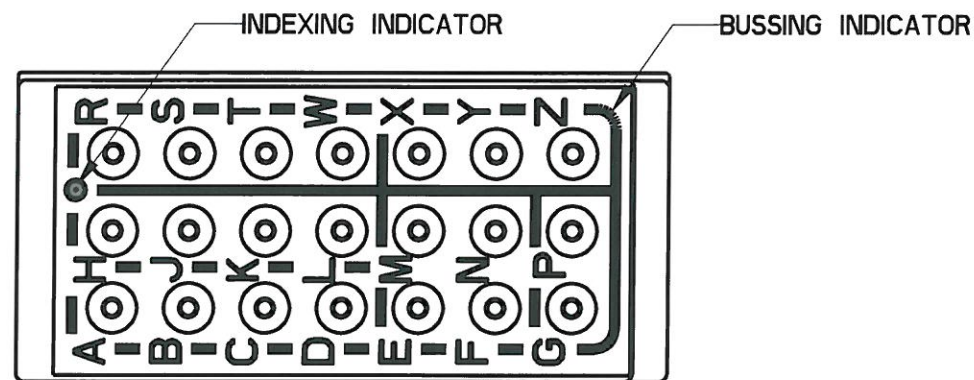
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



REV	ECN	APP'D
-	2939	JR 2/7/97
A	3043	AP 7/22/97
B	3338	JR 7/16/98
C	6200	JT 8/25/08
D	6349	<i>JT 9/27/10</i>



IDENTIFICATION CHARACTERS
.06 HEIGHT

PART NO.	INCLUDED W/ MODULE
TJHD22600	MODULE ONLY
TJHD22700	22 EACH M39029/1-507 PIN CONTACTS 2 EACH MS27488-22 SEALING PLUGS

- NOTES:
1. MATERIAL:
HOUSING - THERMOPLASTIC, COLOR: BLACK.
GROMMET - SILICONE RUBBER, COLOR: BLUE
INTERNAL BUSSING - COPPER ALLOY
2. MODULE ACCEPTS M39029/1-507 PIN CONTACTS

DIMENSIONS	TOLERANCES	PROJECTION	Amphenol Pcd SPECIFICATION DRAWING	
ANSI Y14.5M UNITS: INCHES Pro/E FILE	.XX ±0.01 .XXX ±0.005 ANGLES ±2.0°		ENGR A. PATRIE 03/08/06	
ORIGINAL 	THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION WHICH IS THE CONFIDENTIAL PROPERTY OF AMPHENOL PCD, BEVERLY, MA		CHKD <i>[Signature]</i> 9/27/10	APPD <i>[Signature]</i> 9/27/10

TITLE		
MODULE, TERMINAL JUNCTION SIZE 22, HI-DENSITY D30 BUS ARRANGEMENT		
SIZE B	DWG NO. TJHD22600	REV D
CODE: 58982	SCALE: 4:1	SHEET 1 OF 1

TJHD22600

TJHD22600